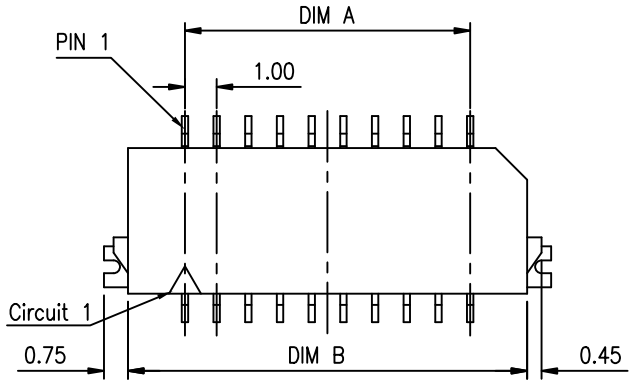
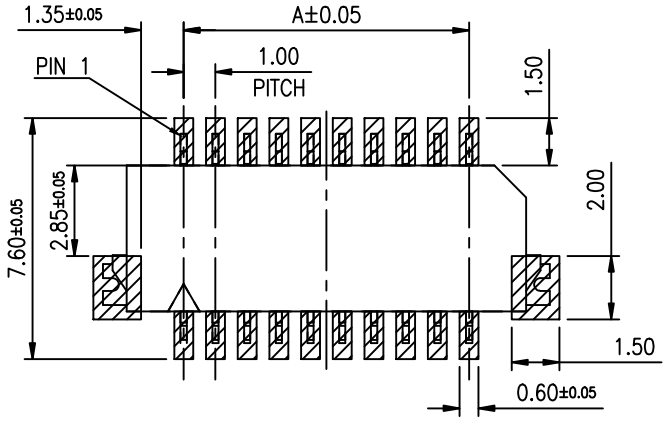


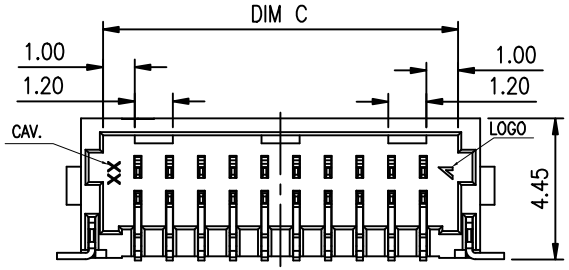


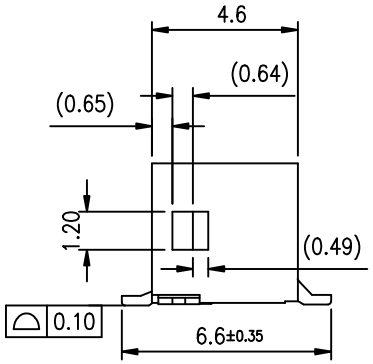
RECOMMANDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

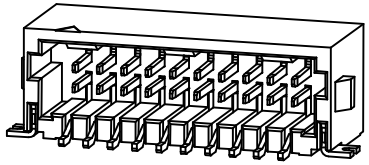
NOTES:
1. MATERIAL:
  1.1 HOUSING: HALOGEN FREE PLASTIC,UL94V-0.
  1.2 CONTACT: COPPER ALLOY
  1.3 FITTING NAIL: COPPER ALLOY
2.FINISH:
2.1 TERMINAL:
  50U" NICKEL UNDERPLATNG OVERALL,
  1:GOLD FLASH OVERALL FOR LEAD FREE.
  A:3u" GOLD ON CONTACT AND GOLD FLASH ON SOLDER AREA
  C:15u" GOLD ON CONTACT AND GOLD FLASH ON OTHER AREA
  D:30u" GOLD ON CONTACT AND GOLD FLASH ON SOLDER AREA
2.2 FITTING NAIL:
  50u" MIN. NICKEL UNDERPLATNG OVERALL.
  100u" MIN. MATTE TIN PLATING
3. REFLOW SOLDER CAPABLE TO 260°C
  PER ACES SPEC.
4. SPEC. PLS. REFER TO PS-50251-XXXXX-XXX
5. PACKAGE PLS. REFER TO 52233-XXXXX-XX-TRP
6.PART NUMBER
  52233-XXX X X-XXX

Ckts
Packing
0:Tape&Reel
1:Tube
Plating
1:GOLD FLASH OVERALL FOR LEAD FREE.
A:3u" GOLD ON CONTACT AREA
C:15u" GOLD ON CONTACT AREA
D:30u" GOLD ON CONTACT AREA

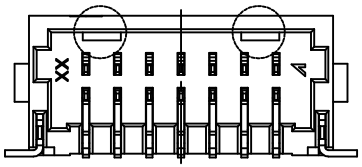
XXX	Material&Color
001	HF Plastic&Black



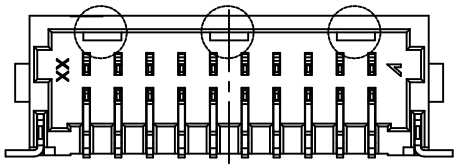




CKTS	DIM A	DIM B	DIM C
010	4.0	7.6	6.2
016	7.0	10.6	9.2
020	9.0	12.6	11.2
030	14.0	17.6	16.2
040	19.0	22.6	21.2
050	24.0	27.6	26.2



For2*4~2*7pin



For2*8~2*25pin

QUALITY SYMBOLS
MAJOR
CRITICAL

GENERAL TOLERANCES
(UNLESS SPECIFIED)
X. ±0.5
.X ±0.25
.XX ±0.15
.XXX ±0.1
ANGLES ±2°

DRAWN BY: GAOLI	DATE: 23'/08/18	ACES ELECTRONICS	
CHECKED BY: XuZhiYong	DATE: 23'/08/18	TITLE: 1.0mm WTB Wafer R/A D/R SMT TYPE	
APPROVED BY: XuZhiYong	DATE: 23'/08/18		
UNITS: mm		SIZE: A4	RFQ NO.: NA
SCALE: 1 : 1	SHEET NO.: 1 OF 1	REV: B	DWG NO.: 52233-XXXXX-XXX